CN Number: 20160725002		- 1	PCN Da	ate: 8/2/2016			
Title: Datasheet f	or LM3559						
Customer Contact:	PCN Manager			De	pt:	Quality Services	
Change Type:							
Assembly Site		Design			Wafer	Bump Site	
Assembly Proces		🛾 Data She	eet			Bump Material	
Assembly Materials			nber change			Bump Process	
Mechanical Specification		Test Site				Fab Site	
Packing/Shipping/Labeling		Test Proc	cess			Fab Materials	
					Wafer	Fab Process	
Notification Details							
	Description of Change: Texas Instruments Incorporated is announcing an information only notification.						
Texas Instruments In	corporated is an	nouncing a	n information or	nly no	otificatio	on.	
The product detector	t(c) ic being was	lated as sin	mmonized heles				
The product datashee	t(s) is being upo	lated as su	mmarized below	•			
The following change	history provides	further de	taile				
The following change	matory provides		cuilo.				
TEXAS INSTRUMENTS						LM3559	
				SNVS624	4B – JUNE 20	11-REVISED JUNE 2016	
Changes from Revision A	(May 2013) to Revisi	on B				Page	
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Added Device Informati tables Easture Departure							
tables, Feature Descript	tion, Device Functional	Modes, Applica	ation and Implementati	on, Pou	wer Supply	/	
	tion, Device Functional rout, Device and Docur	Modes, Applica mentation Suppo	ation and Implementati ort, and Mechanical, P	on, Pov ackagir	wer Supply ng, and Or	/ derable	
tables, Feature Descrip, Recommendations, Lay Information sections • Added Thermal Informa	tion, Device Functional out, Device and Docur tion table with revised	l Modes, Applica mentation Suppo R _{θJA} value (fron	ation and Implementati ort, and Mechanical, P 	on, Pov ackagin C/W") a	wer Supply ng, and Or and additio	/ derable 	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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